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ASM3P2180A

Peak Reducing EMI Solution

Product Description

The ASM3P2180A is a versatile spread spectrum frequency modulator designed specifically for a wide range of clock frequencies. ASM3P2180A reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of down stream clock and data dependent signals. ASM3P2180A allows significant system cost savings by reducing the number of circuit board layers, and shielding that are traditionally required to pass EMI regulations. ASM3P2180A modulates the output of a single PLL in order to "spread" the bandwidth of a synthesized clock, thereby decreasing the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most clock generators. Lowering EMI by increasing a signal's bandwidth is called spread spectrum clock generation. ASM3P2180A uses the most efficient and optimized modulation profile approved by the FCC and is implemented by using a proprietary all-digital method.

Features

- Generates a 1x EMI Optimized Clock Output
- Input Frequency:
 - ◆ 6 MHz 10 MHz
 - ♦ 18 MHz 30 MHz
- Output Frequency:
 - ♦ 6 MHz 10 MHz
 - 18 MHz 30 MHz
- Two Selectable Down Spread Options
- Selectable Frequency Range
- Integrated Loop Filter Components
- Operates with a 3.3 V Supply
- CMOS Design
- 8-Pin SOIC Packages
- This Device is Pb-Free, Halogen Free and is RoHS Compliant

Applications

The ASM3P2180A is targeted towards notebook LCD displays, other displays using an LVDS interface, PC peripheral devices and embedded systems.

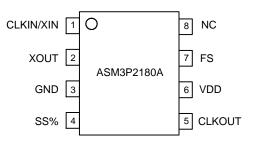


ON Semiconductor®

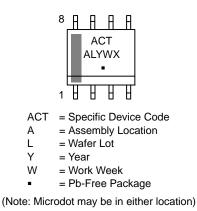
www.onsemi.com



PIN CONNECTION



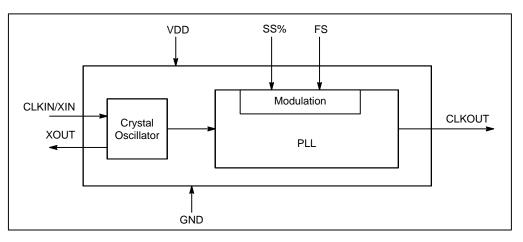
MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

ASM3P2180A





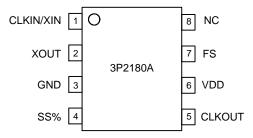




Table 1. PIN DESCRIPTION

Pin#	Pin Name	Туре	Description	
1	CLKIN/XIN	I	Crystal Connection or External Reference Clock Input	
2	XOUT	0	Connection for an External Crystal. If using an External Reference, this Pin must be Left Unconnected	
3	GND	Р	Ground to Entire Chip	
4	SS%	I	Spread Selection Input. Has an Internal Pull-Up Resistor	
5	CLKOUT	0	Modulated Clock Output	
6	VDD	Р	Power Supply for the Entire Chip	
7	FS	I	Frequency Selection Bit. This Pin Selects the Frequency Range of Operation (See Table 2). Has an Internal Pull-Up Resistor	
8	NC	-	No Connect	

Table 2. FREQUENCY RANGE SELECTION

FS	Frequency Range (MHz)
0	6–10
1	18–30

Table 3. SPREAD SELECTION

	Freque	ncy (MHz)	
SS%	FS = 0	FS = 1	Deviation (%) (Typ)
0	6	18	-2
	8	24	-1.5
	10	30	-1
1	6	18	-4
	8	24	-3
	10 30		-2

Table 4. ABSOLUTE MAXIMUM RATINGS

Symbol	Symbol Parameter		Unit
VDD, V _{IN}	Voltage on any Pin with Respect to Ground	-0.5 to +4.6	V
T _{STG}	Storage Temperature	-60 to +125	°C
Τ _S	Maximum Soldering Temperature (10 s)	260	°C
TJ	Junction Temperature	150	°C
T _{DV}	Static Discharge Voltage (as per JEDEC STD22-A114-B)	2	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 5. RECOMMENDED OPERATING CONDITIONS

Parameter	Description	Min	Max	Unit
VDD	Supply Voltage		3.7	V
T _A	T _A Operating Temperature (Ambient Temperature)		+85	°C
C _L Load Capacitance		-	15	pF
C _{IN} Input Capacitance		-	4	pF

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 6. DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Min	Тур	Max	Unit
VIL	Input Low Voltage	GND – 0.3	-	0.8	V
V _{IH}	Input High Voltage	2.0	-	V _{DD} + 0.3	V
Ι _{ΙL}	Input Low Current (Pull-Up Resistors on Inputs SS%, FS)	-	-	-27	μΑ
I _{IH}	Input High Current	-	-	18	μΑ
I _{XOL}	X _{OUT} Output Low Current (@ 0.4 V, V _{DD} = 3.3 V)	-	3	-	mA
I _{XOH}	X _{OUT} Output High Current (@ 2.5 V, V _{DD} = 3.3 V)	-	4	-	mA
V _{OL}	Output Low Voltage (V_{DD} = 3.3 V, I_{OL} = 4 mA)	_	-	0.4	V
V _{OH}	Output High Voltage (V _{DD} = 3.3 V, I _{OH} = 4 mA)	2.5	-	-	V
I _{CC}	Dynamic Supply Current Normal Mode (3.3 V and 10 pF Loading)	10	15	25	mA
I _{DD} *	Static Supply Current Standby Mode	-	-	7	mA
V _{DD}	Operating Voltage	2.8	3.3	3.7	V
t _{ON}	Power-Up Time (First Locked Clock Cycle after Power-Up)	-	0.18	-	ms
Z _{OUT}	Clock Output Impedance	-	50	-	Ω

* CLKIN pin pulled to GND.

Symbol	Parameter	Min	Тур	Max	Unit
CLKIN	Input Frequency FS = 0 FS = 1	6 18		10 30	MHz
CLKOUT	Output Frequency FS = 0 FS = 1	6 18		10 30	MHz
t _{LH} *	Output Rise Time (Measured at 0.8 V to 2.0 V)	1.2	1.3	1.4	ns
t _{HL} *	Output Fall Time (Measured at 2.0 V to 0.8 V)	0.8	0.9	1.0	ns
t _{JC}	Jitter (Cycle to Cycle)	-	±325	-	ps
t _D	Output Duty Cycle	45	50	55	%

Table 7. AC ELECTRICAL CHARACTERISTICS

* t_{LH} and t_{HL} are measured into a capacitive load of 15 pF.

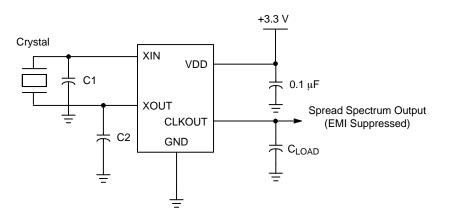


Figure 3. Typical Test Circuit

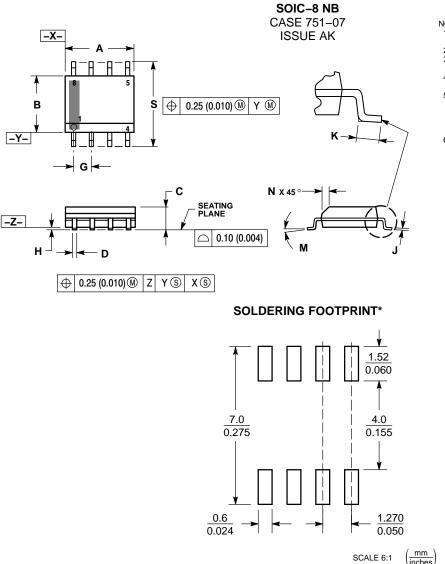
Table 8. ORDERING INFORMATION

Part Number	Marking	Package	Temperature	Shipping [†]
ASM3P2180AF-08SR	ACT	SOIC–8 NB (Pb-Free)	0 to 70°C	2500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, <u>BRD8011/D</u>.

ASM3P2180A

PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 1.
- CONTROLLING DIMENSION: MILLIMETER. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION. 3.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) 4 PER SIDE
- PER SIDE: DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT 5. MAXIMUM MATERIAL CONDITION
- 751-01 THRU 751-06 ARE OBSOLETE. NEW 6. STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.053	0.069		
D	0.33	0.51	0.013	0.020		
G	1.27	7 BSC	0.05	0 BSC		
н	0.10	0.25	0.004	0.010		
J	0.19	0.25	0.007	0.010		
к	0.40	1.27	0.016	0.050		
м	0 °	8 °	0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228 0.244			

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